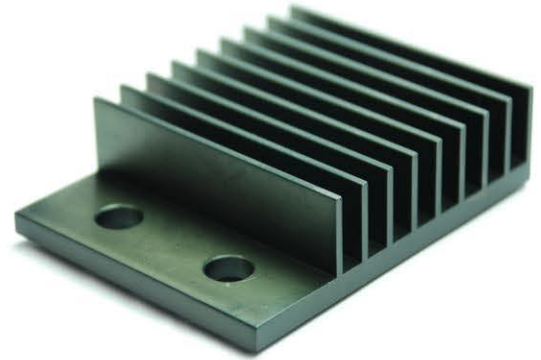




FEMA Electronics has been specializing in heat sinks and other thermal management products since 1995.

FEMA Electronics' operation is also geared to provide our customers with custom parts and complete design services in order to meet their special needs for thermal treatment. We can perform minor modification on our standard parts to achieve cost savings for our customers.



Wide Product Selection



Extruded Heat Sink



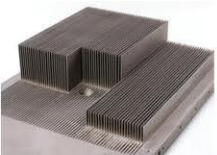
Stamped Heat Sink



Bonded Heat Sink



BGA & PGA Heat Sink



Epoxy Fins Heat Sink



Liquid Cooled Heat Sink

Heat Sink Products

- * Extruded Heat Sinks (Standard & Custom)
- * Stamped Heat Sinks (Standard & Custom)
- * Microprocessor Heat Sinks
- * Assembled Fin
- * Folded Fin
- * Surface Mount Heat Sinks
- * Liquid Cooled Heat Sinks
- * Bonded Heat Sinks
- * BGA & PGA Heat Sinks
- * Epoxy Fins Heat Sinks

Technical Capabilities

- * Perform secondary operations such as tapping, anodize, extrusions & cutting
- * Extrusions can be made to custom width, length and fin height
- * Extrusion flatness: 0.002"/" to 0.0005"/"
- * Machined flatness: 0.001"/" of width
- * Stamped heat sinks (PC Board Level)
- * Assembled and bonded fins: (fins attached by press machine or epoxy)
- * Interface materials: thermal adhesives, double-sided tape, silicon pads
- * Types of finishes: clear anodize, black anodize, red anodize, blue anodize, clear chromate, gold chromate, tin-plate, pre-tinned copper, electronic coating, clean

Options and Accessories

- * Clips, hardware and solderable tabs available for mounting and assembling the semiconductors to heat sinks
- * Interface material can be applied to the sinks (silicon pad, thermal adhesive, double sided tape)